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SUBMISSION TYPE:			NEW ASSIGNMENT								
NATURE OF CONVEYANCE:			ASSIGNMENT								
CONVEYING PARTY	DATA										
		lame	Execution Date								
Yuichi GONDO	05/27/2011										
Hideyasu MATSUMU	05/27/2011										
RECEIVING PARTY DATA											
Name: SEKISUI PLASTICS CO., LTD.											
Street Address:	4-4, Nishitenma 2-chome, Kita-ku, Osaka-shi,										
City:	Osaka										
State/Country:	JAPAN										
Postal Code:	5300047										
PROPERTY NUMBERS Total: 1											
Property Type			Number								
Application Number: 13140			231		13140231						
CORRESPONDENCE	DATA										
Fax Number:	(703)716-	-1180			\$40.00						
Correspondence will b	oe sent via US N	Mail w	hen the fax attempt is unsuccessful.		\$4(
Phone:	703-716-				OP						
Correspondent Name: GREENBLUM & BERNSTEIN, P.L.C. Address Line 1: 1950 ROLAND CLARKE PLACE											
Address Line 4: RESTON, VIRGINIA 20191											
ATTORNEY DOCKET NUMBER:			P40268								
NAME OF SUBMITTER:			Daniel M. Moon								
Total Attachments: 2 source=p40268_assignmen#page1.tif source=p40268_assignmen#page2.tif											

(US ONLY - TWO INVENTORS/SINGLE ASSIGNEE/APPLICATION FILED)

ASSIGNMENT

WHEREAS, <u>Yuichi GONDO</u>, a citizen of <u>Japan</u>, whose post office address is <u>c/o SEKISUI</u> <u>PLASTICS CO., LTD., 1259 Minakuchicho Izumi, Koka-shi, Shiga 5280056 Japan</u> and <u>Hideyasu</u> <u>MATSUMURA</u>, a citizen of <u>Japan</u>, whose post office address is <u>c/o SEKISUI PLASTICS CO.,</u> <u>LTD., 1259 Minakuchicho Izumi, Koka-shi, Shiga 5280056 Japan</u> hereinafter referred to as the ASSIGNORS, have invented a certain improvement relating to

"PRE-EXPANDED PARTICLES, PROCESS FOR PRODUCING THE SAME AND EXPANDED MOLDED ARTICLE"

for which they have jointly executed an application for Letters Patent for the United States which was filed in the United States Patent and Trademark Office on ______ and was awarded Application No. ______.

OPTIONAL

If this Assignment is filed after the filing date of the above-identified application, the undersigned hereby authorize and request any one of the attorneys of record in this application including Neil F. Greenblum, Reg. No. 28,394, Bruce H. Bernstein, Reg. No. 29,027, Arnold Turk, Reg. No. 33,094, James L. Rowland, Reg. No. 32,674, Stephen M. Roylance, Reg. No. 31,296, Leslie J. Paperner, Reg. No. 33,329, William Pieprz, Reg. No. 33,630, Robert W. Mueller, Reg. No. 35,043 and William E. Lyddane, Reg. No. 41,568, of the firm Greenblum & Bernstein, P.L.C., whose address is 1950 Roland Clarke Place, Reston, Virginia 20191, to insert here in parenthesis (Application No. ______, filed ______) the filing date and application number of said application when known.

AND WHEREAS, <u>SEKISUI PLASTICS CO., LTD.</u>, a corporation organized and existing under the laws of the State of Japan, whose post-office address is <u>4-4</u>, <u>Nishitenma 2-chome</u>, <u>Kita-ku</u>, <u>Osaka-shi</u>, <u>Osaka 5300047 Japan</u>, hereinafter known as the ASSIGNEE, is desirous of acquiring the entire right, title and interest for the United States in and to said invention and application, including any and all divisions and continuations thereof, and any and all Letters Patent which may be granted thereon, including any and all renewals, reissues, and prolongations thereof.

NOW, THIS WITNESSETH that for and in consideration of One Dollar (\$1.00) and other good and valuable consideration, the receipt whereof is hereby acknowledged, said ASSIGNORS hereby assign, sell and transfer to said ASSIGNEE, its assigns and legal representatives, the entire and exclusive right, title and interest in and to said invention and application, for the United States including any and all divisions and continuations thereof, and any and all Letters Patent which may be granted therefor and all rights to sue for past and future infringement thereunder, said ASSIGNEE and its assigns and legal representatives to have, hold, exercise and enjoy the said invention and application, including any and all divisions and continuations thereof, and any and all Letters Patent which may be granted thereon, including any and all renewals, reissues and prolongations thereof, with all the rights, powers, privileges, and advantages in any ways arising

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PATENT REEL: 026459 FRAME: 0217 from or pertaining thereto, for and during the term or terms of any and all such Letters Patent when granted, including any and all renewals, reissues, and prolongations thereof, for the use and benefit of said ASSIGNEE and its assigns and legal representatives in as ample and beneficial a manner to all intents and purposes as the said ASSIGNORS might or could have held and enjoyed the same, if this assignment had not been made.

AND said ASSIGNORS hereby agree to execute all papers necessary to file applications in the United States for said invention and to assign the same to said ASSIGNEE, or any assignee acquiring title to said invention, and to execute any other papers that may be needed in connection with filing said application and securing Letters Patent thereon.

AND said ASSIGNORS authorize and request the Commissioner of Patents to issue Letters Patent on said application, and on any and all divisions and continuations thereof, to said ASSIGNEE, its assigns and legal representatives, in accordance herewith.

(Date) 27/05/2011 Yuichi Gondo

(Date) 27/05/2011

Hideyasu hatsumura

Hideyasu MATSUMURA

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PATENT REEL: 026459 FRAME: 0218

RECORDED: 06/16/2011